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ELECTRONICS

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Jameco Part Number 1623349

# GaAlAs-IR-Lumineszenzdioden (880 nm) GaAlAs Infrared Emitters (880 nm)

# Lead (Pb) Free Product - RoHS Compliant

# SFH 484 SFH 485





SFH 484 SFH 485

### Wesentliche Merkmale

- GaAlAs-LED mit sehr hohem Wirkungsgrad
- Hohe Zuverlässigkeit
- Gute spektrale Anpassung an Si-Fotoempfänger
- Gegurtet lieferbar (im Ammo-Pack)
- Gruppiert lieferbar
- SFH 484: Gehäusegleich mit LD 274
- SFH 485: Gehäusegleich mit SFH 300, SFH 203

### Anwendungen

- IR-Fernsteuerung von Fernseh- und Rundfunkgeräten, Videorecordern, Lichtdimmern
- Gerätefernsteuerungen für Gleich- und Wechsellichtbetrieb
- Rauchmelder (UL-Freigabe)
- Sensorik
- Diskrete Lichtschranken

### **Features**

- Very highly efficient GaAlAs-LED
- High reliability
- Spectral match with silicon photodetectors
- Available on tape and reel (in Ammopack)
- Available in bins
- SFH 484: Same package as LD 274
- SFH 485: Same package as SFH 300, SFH 203

### **Applications**

- IR remote control of hi-fi and TV-sets, video tape recorders, dimmers
- Remote control for steady and varying intensity
- Smoke detectors (UL-approval)
- Sensor technology
- · Discrete interrupters

Typ Type	Bestellnummer Ordering Code	Gehäuse Package
SFH 484	Q62703Q1092	5-mm-LED-Gehäuse (T 1 <sup>3</sup> / <sub>4</sub> ), klares violettes
SFH 484-2	Q62703Q1756	Epoxy-Gießharz, Anschlüsse im 2.54-mm-Raster (1/10"), Anodenkennzeichung: kürzerer Anschluß
SFH 485	Q62703Q1093	5 mm LED package (T 1 <sup>3</sup> / <sub>4</sub> ), violet-colored epoxy resin,
SFH 485-2	Q62703Q1547	solder tabs lead spacing 2.54 mm (1/10"), anode marking: short lead

2004-12-20



# **Grenzwerte** ( $T_A = 25$ °C) **Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{ m op};T_{ m stg}$	- 40 <b>+</b> 100	°C
Sperrspannung Reverse voltage	$V_{R}$	5	V
Durchlaßstrom Forward current	$I_{F}$	100	mA
Stoßstrom, $t_p = 10 \mu s$ , $D = 0$ Surge current	$I_{FSM}$	2.5	А
Verlustleistung Power dissipation	P <sub>tot</sub>	200	mW
Wärmewiderstand, freie Beinchenlänge max. 10 mm Thermal resistance, lead length between package bottom and PC-board max. 10 mm	R <sub>thJA</sub>	375	K/W



# Kennwerte ( $T_A$ = 25 °C) Characteristics

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der Strahlung Wavelength at peak emission $I_{\rm F}$ = 100 mA	$\lambda_{peak}$	880	nm
Spektrale Bandbreite bei 50% von $I_{rel}$ Spectral bandwidth at 50% of $I_{rel}$ $I_{F}$ = 100 mA	Δλ	80	nm
Abstrahlwinkel Half angle SFH 484 SFH 485	φ	± 8 ± 20	Grad deg.
Aktive Chipfläche Active chip area	A	0.09	mm <sup>2</sup>
Abmessungen der aktiven Chipfläche Dimension of the active chip area	$L \times B \\ L \times W$	0.3 × 0.3	mm
Abstand Chipoberfläche bis Linsenscheitel Distance chip front to lens top SFH 484 SFH 485	H H	5.1 5.7 4.2 4.8	mm mm
Schaltzeiten, $I_{\rm e}$ von 10% auf 90% und von 90% auf 10%, bei $I_{\rm F}$ = 100 mA, $R_{\rm L}$ = 50 $\Omega$ Switching times, $I_{\rm e}$ from 10% to 90% and from 90% to 10%, $I_{\rm F}$ = 100 mA, $R_{\rm L}$ = 50 $\Omega$	$t_{\rm r},t_{\rm f}$	0.6/0.5	μs
Kapazität Capacitance $V_{\rm R}$ = 0 V, $f$ = 1 MHz	$C_{o}$	15	pF
Durchlaßspannung Forward voltage $I_{\rm F}$ = 100 mA, $t_{\rm p}$ = 20 ms $I_{\rm F}$ = 1 A, $t_{\rm p}$ = 100 $\mu$ s	$egin{array}{c} V_{F} \ V_{F} \end{array}$	1.50 (≤ 1.8) 3.00 (≤ 3.8)	V V
Sperrstrom, Reverse current $V_{\rm R} = 5 \text{ V}$	$I_{R}$	0.01 (≤ 1)	μΑ
Gesamtstrahlungsfluß, Total radiant flux $I_{\rm F}$ = 100 mA, $t_{\rm p}$ = 20 ms	$\Phi_{e}$	25	mW



Kennwerte ( $T_A = 25$  °C) Characteristics (cont'd)

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Temperaturkoeffizient von $I_e$ bzw. $\Phi_e$ , $I_F$ = 100 mA Temperature coefficient of $I_e$ or $\Phi_e$ , $I_F$ = 100 mA	TC <sub>I</sub>	- 0.5	%/K
Temperaturkoeffizient von $V_{\rm F},I_{\rm F}$ = 100 mA Temperature coefficient of $V_{\rm F},I_{\rm F}$ = 100 mA	$TC_{V}$	- 2	mV/K
Temperaturkoeffizient von $\lambda$ , $I_{\rm F}$ = 100 mA Temperature coefficient of $\lambda$ , $I_{\rm F}$ = 100 mA	$TC_{\lambda}$	0.25	nm/K

### Gruppierung der Strahlstärke $I_{\rm e}$ in Achsrichtung

gemessen bei einem Raumwinkel  $\Omega$  = 0.001 sr bei SFH 484 bzw.  $\Omega$  = 0.01 sr bei SFH 485

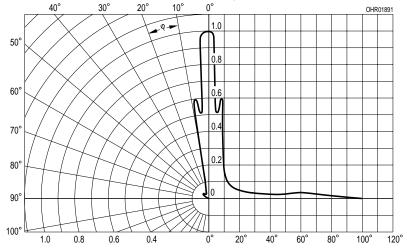
# Grouping of Radiant Intensity $\mathbf{I}_{\mathbf{e}}$ in Axial Direction

at a solid angle of  $\Omega$  = 0.001 sr at SFH 484 or  $\Omega$  = 0.01 sr at SFH 485

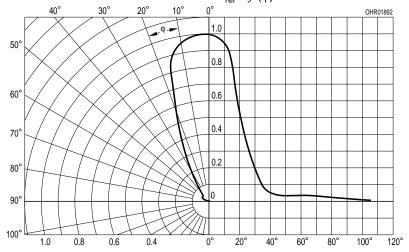
Bezeichnung Parameter	Symbol	Wert Value					Einheit Unit
		SFH 484	SFH 484-1	SFH 484-2	SFH 485	SFH 485-2	
Strahlstärke Radiant intensity $I_{\rm F} = 100 \text{ mA}, t_{\rm p} = 20 \text{ ms}$	$I_{ m e\ min}$ $I_{ m e\ max}$	50	50 100	80	25 160	25 100	mW/sr mW/sr
Strahlstärke Radiant intensity $I_F = 1 \text{ A}, t_p = 100 \mu\text{s}$	I <sub>e typ.</sub>	800	700	900	300	340	mW/sr



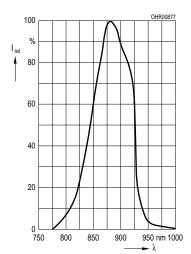
# Radiation Characteristics, SFH 484 $I_{\text{rel}}$ = $f\left(\phi\right)$



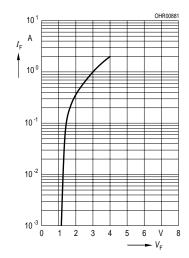
### Radiation Characteristics SFH 485 $I_{rel} = f(\phi)$



# Relative Spectral Emission $I_{rel} = f(\lambda)$

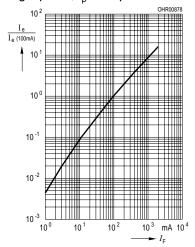


# Forward Current $I_F = f(V_F)$ , single pulse, $t_p = 20 \mu s$

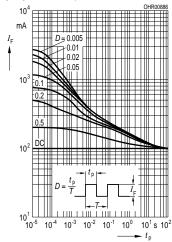


# Radiant Intensity $\frac{I_{\rm e}}{I_{\rm e}\,{\rm 100~mA}}$ = f ( $I_{\rm F}$ )

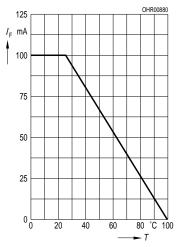
Single pulse,  $t_p = 20 \mu s$ 



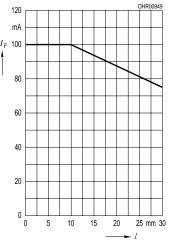
Permissible Pulse Handling Capability  $I_{\rm F}$  = f ( $\tau$ ),  $T_{\rm A}$  = 25 °C, duty cycle D = parameter



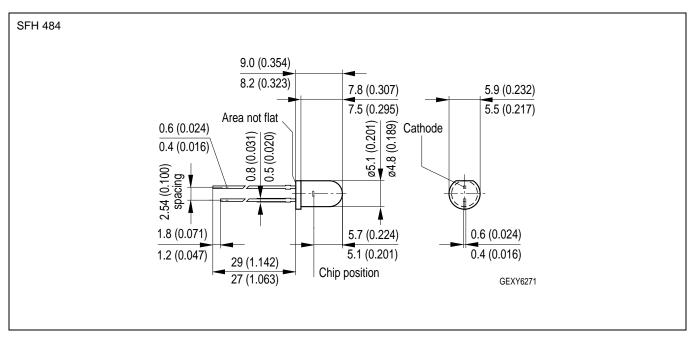
# Max. Permissible Forward Current $I_{\rm F} = f\left(T_{\rm A}\right)$

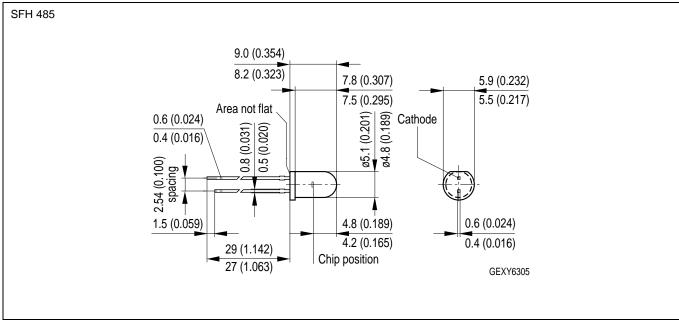


Forward Current vs. Lead Length between the Package Bottom and the PC-Board  $I_F = f(l)$ ,  $T_A = 25 \, ^{\circ} \times C$ 



### Maßzeichnung Package Outlines





Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).



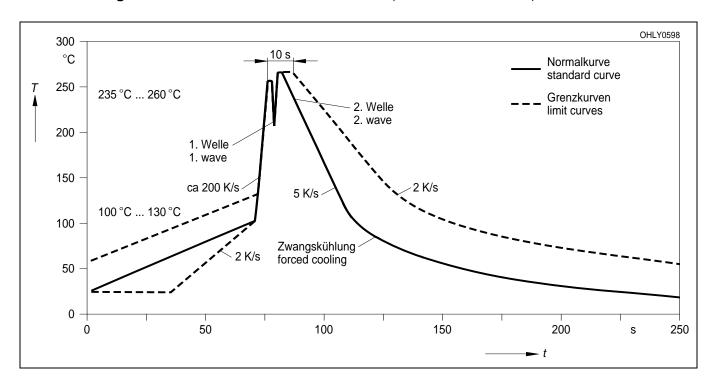
# Empfohlenes Lötpaddesign Recommended Solder Pad TTW Soldering OHLPY985

Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

**OSRAM** 

Lötbedingungen Soldering Conditions Wellenlöten (TTW) TTW Soldering

(nach CECC 00802) (acc. to CECC 00802)



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